

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

Claims 1-12 (canceled).

Claim 13 (currently amended) A heat pipe cooler, comprising:
a heat receiving plate having lower and upper opposite surfaces, said lower surface of
said heat receiving plate arranged to contact a semiconductor element which generates heat and is
to be cooled;
a plurality of heat pipes fixed to flat portions of said upper surface of said heat receiving
plate for thermal conduction, said plurality of heat pipes being upstanding with respect to said
heat receiving plate, and said plurality of heat pipes being sealed at opposite end portions thereof;
a plurality of parallel heat radiating plates fixed to said plurality of heat pipes at positions
along said plurality of heat pipes toward an end thereof, said parallel heat radiating plates
extending substantially parallel to, and having a shape corresponding to said heat receiving plate;
a distance between said heat receiving plate and one of said parallel heat radiating plates
which is located adjacent the heat receiving plate being substantially greater than a distance
between two adjacent said parallel heat radiating plates;

a ventilation duct having an air inlet and air outlet surrounding said parallel heat radiating plates and defining a passage for air through a gap between said parallel heat radiating plates; and a fan producing a current of air through said duct,
wherein said heat pipe has a generally U-shaped or V-shaped profile, [[and]]
wherein said heat receiving plate is arranged entirely outside said ventilation duct to permit cooling of said semiconductor element ~~without affecting other elements surrounding said semiconductor element, and~~
wherein each of the plurality of heat pipes is located at a slant with respect to said heat receiving plate so that cooling air directly collides not only with upstream heat pipe end portions, but also with downstream heat pipe end portions, thereby improving heat radiation from the plurality of heat pipes.

Claim 14 (previously presented) The heat pipe cooler according to claim 13, wherein each of said opposite end portions of said plurality of heat pipes passes through said plurality of parallel heat radiating plates.

Claim 15 (canceled).

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Claim 16 (previously presented) The heat pipe cooler according to claim 13, wherein both said opposite end portions of each of said heat pipes are fixed to each of said plurality of parallel heat radiating plates.

Claim 17-19 (canceled).